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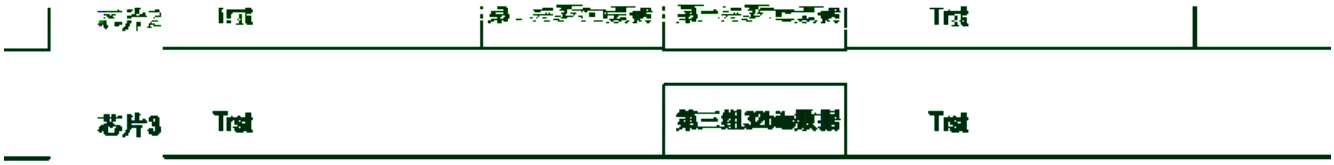

1 MCU 2 3

Note: D1 refers to the data sent by MCU, and D2, D3 and D4 refer to the data automatically shaped and forwarded by cascade circuit

32bit

GRBW

Note: high order first send, send data in the order of GrB

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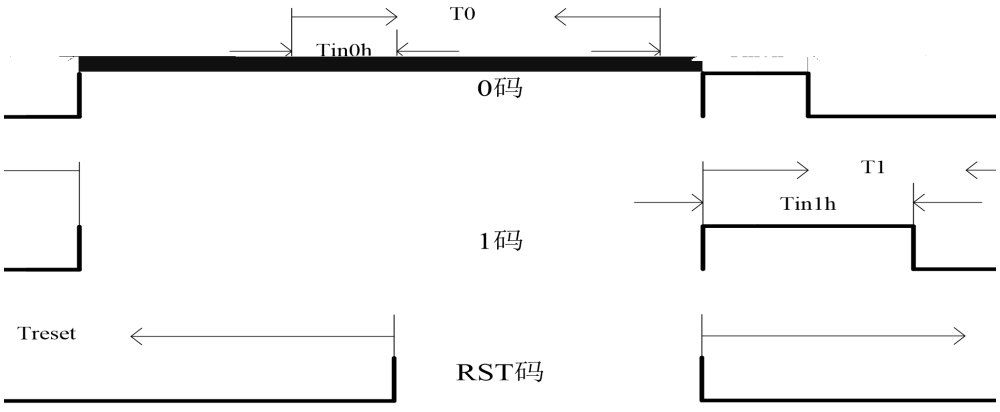


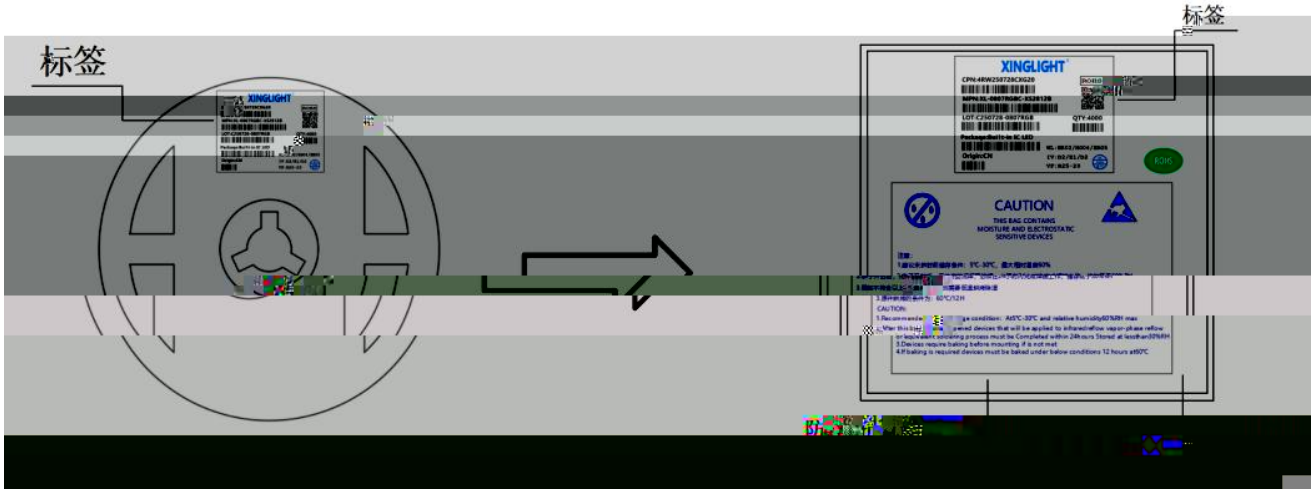
Part

Part

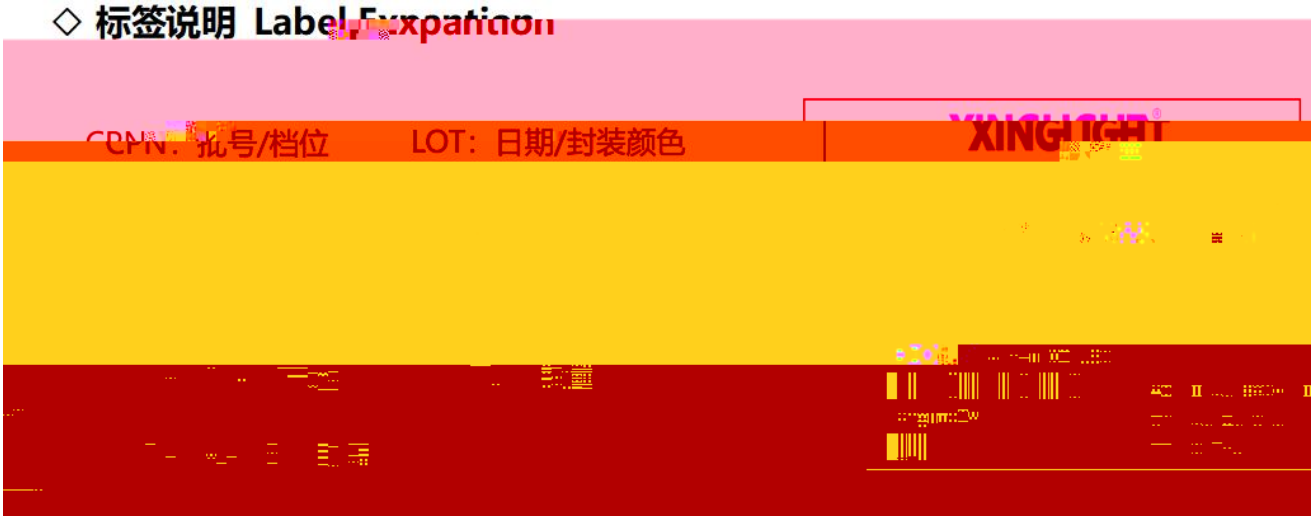
包装（2）

Packaging (2)

◇ 防潮抗静电包装 Moisture Proof and Antti-Electrostic Foil Bag



◇ 标签说明 Label Explanation



XINGLIGHT®

Part No.

焊接指导（1）

Guideline for Solder

使用烙铁人手

30

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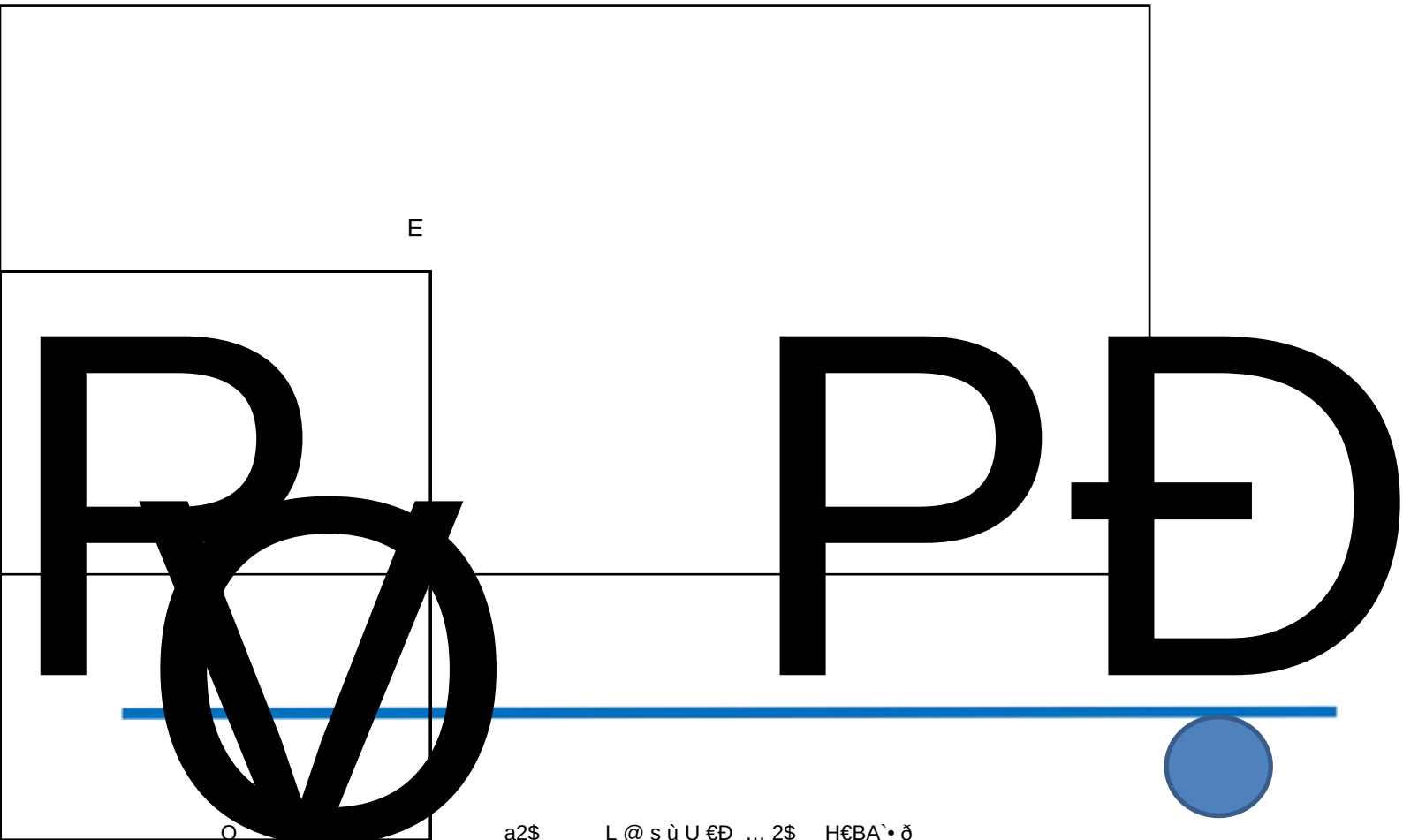

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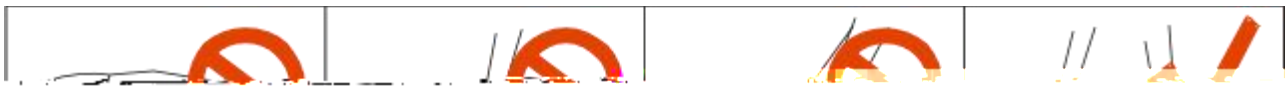
Part

使用注意事项（3）

Precautions (3)

其他事项



眼睛保护忠告：